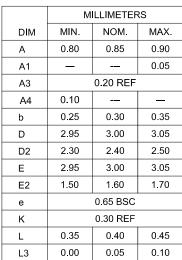


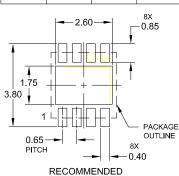
DFNW8 3x3, 0.65P CASE 507AB **ISSUE E**

DATE 02 JUL 2021

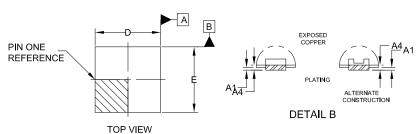


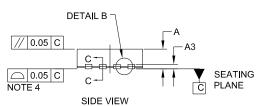
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSION b APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP.
- 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- 5. THIS DEVICE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.

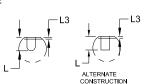




MOUNTING FOOTPRINT



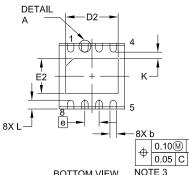




DETAIL A

SECTION C-C

PLATED SURFACES



0.10M C A B NOTE 3 **BOTTOM VIEW**

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

= Assembly Location Α L = Wafer Lot

Υ = Year W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DFNW8 3x3, 0.65P		PAGE 1 OF 1

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